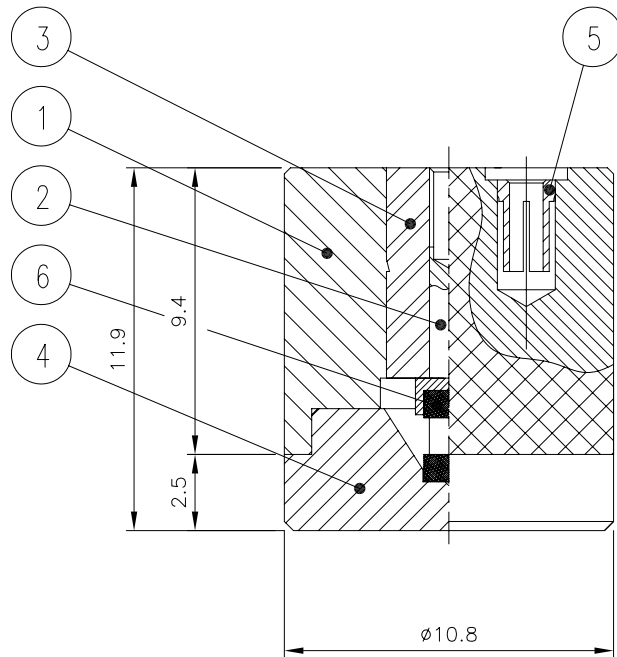
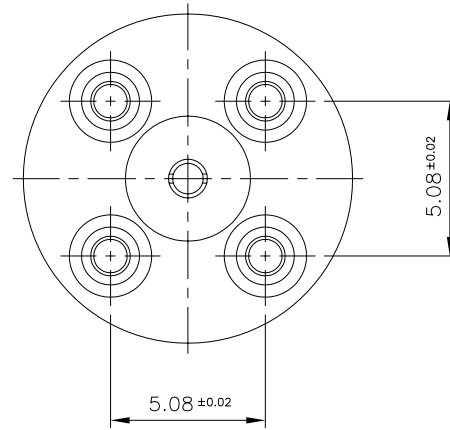


REVISION		
REV	DESCRIPTION	DATE
1 R	최초개정	2009.05.21.



작업지도서

- BODY ①에 Jack⑤(4EA)와 절연체③를 삽입 한다.
- BODY ①에 삽입된 절연체③에 PIN②를 그림과 같이 삽입 한다.
- 조립된 PIN에 저항을 삽입한다.
- 조립된 Body와 Cover를 억지 끼움 한다.
- 멀티미터기로 순수 저항 값을 측정 할 것.
(저항값 : $48\Omega \sim 52\Omega$)

6	RESISTOR	1			DRE00057-N/1 (XA118)
5	JACK	4	BeCu	Gold Plate	DJA00128-5/1
4	COVER	1	MBsBD	Nickel Plate	DCV00043-5/1 (L9005)
3	INSULATOR	1	TEFLON		DIN00131-N/1 (H2246)
2	CONTACT	1	BeCu	Gold Plate	DCT01318-5/1
1	BODY	1	MBsBD	Nickel Plate	DBD02475-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2009. 05. 21.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	S.J.YOUN	
MATERIAL		CHECKED BY	E.H.KIM	KJ COMTECH CO.,LTD. TITLE PCB-4R 내장용 TERM
		DRAWN BY	I.C.KIM	
FINISH		SCALE	UNIT	A4 DWG NO. TM00097-7/1 REVISION I R SHEET 1 of 1
		6/1	mm	